

## High electrical & thermal conductivity

0121 is a one-component, silver-filled, electrically conductive, precision mixed, degassed, and frozen epoxy. It has a long work life, high electrical and thermal conductivity (2.2 W/mK), and a volume resistivity of 6.0E -4 (ohm-cm). These features make it ideal for microelectronic, optoelectronic, and thermal management applications. This material has a long pot life, which maintains its dispensability for 2 days, making it suitable for automated dispensing; it can also be cured quickly at elevated temperatures. 0121 also has a high thixotropic index of 3.69. User-friendly packaging allowing for easy dispensing.

<b>UNCURED</b>	
Pot Life (hr)	48
Viscosity (cps)	2,250
Work Life (Days)	2
Shelf Life @ < -40°C	12 months
<b>CURE OPTIONS</b>	20 minutes @ 120°C (recommended) 1.5 hours @ 80°C    45 seconds @ 175°C 5 minutes @ 150°C
<b>CURED PROPERTIES</b>	
Color	Silver
Lap Shear 2024T3 Clad FPL Etch (psi)	1,500
Shore Hardness	D/80/0
Specific Gravity	2.70
<b>ELECTRICAL PROPERTIES</b>	
Volume Resistivity (ohm*cm)	6.0E - 4
<b>THERMAL PROPERTIES</b>	
Degradation Temp (°C)	410
Glass Transition Temp (°C)	80
Thermal Conductivity (BTU (in)/(hr)(ft²)(°F)	15
Thermal Conductivity (Watt)/(mK)	2.2
<b>OUTGASSING PROPERTIES</b>	
CVCM (%)	0.00
TML (%)	0.19

### KEY FEATURES

Bonds Well to Most Substrates

Fast Elevated Temperature Cure

High Electrical Conductivity

High Thermal Conductivity

Long Work Life

User-friendly Packaging

### Talk to an engineer:

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